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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/616,198	07/09/2003	Hyung Jun Kim	29936/39457	9666
	590 05/06/2005		EXAMINER	
MARSHALL, GERSTEIN & BORUN LLP 233 S. WACKER DRIVE, SUITE 6300			UMEZ ERONINI, LYNETTE T	
SEARS TOWER CHICAGO, IL 60606		ART UNIT	PAPER NUMBER	
			1765	

DATE MAIL ED: 05/06/200

Please find below and/or attached an Office communication concerning this application or proceeding.



	Application No.	Applicant(s)	
Office Action Summary	10/616,198	KIM, HYUNG JUN	
omet Action Gammary	Examiner	Art Unit	
The MAN INC DATE AND	Lynette T. Umez-Eronini	1765	
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with t	the correspondence address	
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION. Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. If the period for reply septicified above, the maximum statutory period, the period for reply septicified above, the maximum statutory period. Experience of the control of the controlled period for reply will, by statute Any reply received by the Colin extended period for reply will, by statute and prophy received by the Colin extended period from these months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply by within the statutory minimum of thirty (30 will apply and will expire SIX (6) MONTHS	be timely filed –) days will be considered timely, from the mailing date of this communication	
Status			
1) Responsive to communication(s) filed on 7/9/2	2003.		
0.10	action is non-final.	j.	
Since this application is in condition for allower	nce except for formal matters	prosecution as to the mort-	
closed in accordance with the practice under E	x parte Quavle, 1935 C D 11	453 O G 213	
Disposition of Claims		, 400 0.0. 210.	
4) Claim(s) 1 is/are pending in the application.		•	
4a) Of the above claim(s) is/are withdraw 5) ☐ Claim(s) is/are allowed.	vn from consideration.		
6) Claim(s) 1 is/are rejected.			
7) Claim(s) is/are rejected.			
8) Claim(s) srate objected to.			
8) Claim(s) are subject to restriction and/or	election requirement.		
Application Papers			
 The specification is objected to by the Examiner 			
10) ☐ The drawing(s) filed on <u>09 July 2003</u> is/are: a) ∑	accepted or b) □ objected t	o by the Examiner	
Applicant may not request that any objection to the d	frawing(s) be held in abevance.	See 37 CFR 1 85(a)	
Replacement drawing sheet(s) including the correction	on is required if the drawing(s) is	objected to Soc 27 CED 4 404(4)	
11) The oath or declaration is objected to by the Exa	aminer. Note the attached Offi	ice Action or form PTO-152.	
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign p	priority under 35 U.S.C. 8 119	(a)-(d) or (f)	
a)⊠ All b) Some * c) None of:		(4) (4) (1).	
 Certified copies of the priority documents 	have been received.		
 Certified copies of the priority documents 	have been received in Applic.	ation No	
Copies of the certified copies of the priorit	y documents have been rece	ived in this National Stage	
application from the International Bureau ((PCT Rule 17.2(a)).		
* See the attached detailed Office action for a list of	f the certified copies not recei	ved.	
Attachment(s)	•		
Notice of References Cited (PTO-892)	ο C1		
Notice of Draftsperson's Patent Drawing Review (PTO 048)	4) Interview Summa Paper No(s)/Mail	Date	
Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)	5) Notice of Informal	Patent Application (PTO-152)	

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DETAILED ACTION

Claim Rejections - 35 USC § 102/103

- The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).
- Claim 1 is rejected under 35 U.S.C. 102(b) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Li et al. (US 6,251,784 B1).

Li teaches chemically mechanically polishing a substrate 100 with a target film of oxide (SiO₂) 104 over a stopping film if nitride (Si₃N₄) 102 using a slurry containing wafer and fumed silica and having a pH of 10.5 (column 3, lines 49-60). Li also teaches, detecting a polishing endpoint by removing the target film with a process that generates a chemical reaction product from the target film or the stopping film or both; converting

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the chemical reaction product into a separate product; exposing the separate product to ionizing radiation; and monitoring the ionization current generated by the radiation as the target film is being removed. A change in the current indicates a change in the concentration of the separate product, and therefore in the concentration of the chemical reaction product (column 2, lines 36-51). The above reads on,

A method of detecting a polishing end point in a chemical mechanical polishing process, comprising the steps of:

using a sensor detecting variation in the concentration of a material within an initial polishing layer or a material within a polishing stop layer, which are contained in polishing wastewater drained during a polishing process.

Li further teaches, "A change in the current indicates a change in the concentration... of the chemical reaction product. This change can be correlated to the process endpoint, thereby providing real-time, ... process control" (column 2, lines 48-53) and "... the sensing current 441 from the detection unit 400, may advantageously include a computer executing a control program to monitor the CMP process and determine the process endpoint. When the endpoint of the CMP process is reached, the computer may send a control signal to the polishing apparatus 10 to terminate the film removal process. The controller 500 also receives a start signal from the polishing apparatus 10, which triggers the program to being monitoring the endpoint signal automatically..." (column 6, lines 1-18). The aforementioned reads on,

using an EDP system to database information detected by the sensor; and

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feeding back the result to a polisher in real time, wherein if a result that there is no change in the concentration of the material within the initial polishing layer is obtained, the polishing process continuously proceeds with an initial polishing process condition.

Li differs in failing to specifically disclose

if a result that variation in the concentration of the material within the initial polishing layer is not reduced but kept constant and variation in the concentration of the material within the polishing stop layer is not increased but kept constant, is obtained, using the EPD system to send a polishing process stop signal to the polisher, thus stopping the polishing process; and

if a result that variation in the concentration of the material within the initial polishing layer is reduced and variation in the concentration of the material within the polishing stop layer is increased, is obtained, performing the polishing process by lowering a polishing pressure.

However, the presently claimed feature, if a result that variation in the concentration of the material within the initial polishing layer is not reduced but kept constant and variation in the concentration of the material within the polishing stop layer is not increased but kept constant, is obtained, using the EPD system to send a polishing process stop signal to the polisher, thus stopping the polishing process; and

if a result that variation in the concentration of the material within the initial polishing layer is reduced and variation in the concentration of the material within the polishing stop layer is increased, is obtained, performing the polishing process by lowering a polishing pressure, in the said claim, would Application/Control Number: 10/616,198

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obviously have been provided as a result of using Li's endpoint detection method in the same manner as those of the claimed invention

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lynette T. Umez-Eronini whose telephone number is 571-272-1470. The examiner is normally unavailable on the First Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on 571-272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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PRIMARY EXA

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May 2, 2005